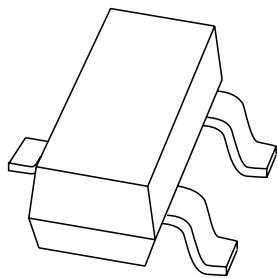


DATA SHEET



BF840

NPN medium frequency transistor

Product specification
Supersedes data of 1999 Apr 12

2004 Jan 13

NPN medium frequency transistor

BF840

FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 40 V).

APPLICATIONS

- AM mixers
- IF amplifiers in AM/FM receivers.

DESCRIPTION

NPN medium frequency transistor in a SOT23 plastic package.

MARKING

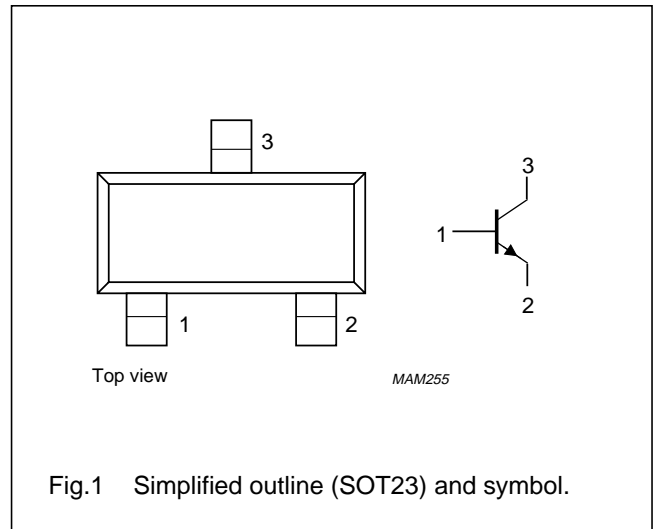
| TYPE NUMBER | MARKING CODE ⁽¹⁾ |
|-------------|-----------------------------|
| BF840 | NC* |

Note

- * = p : Made in Hong Kong.
 * = t : Made in Malaysia.
 * = W : Made in China.

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | base |
| 2 | emitter |
| 3 | collector |



ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|-------------|---------|--|---------|
| | NAME | DESCRIPTION | VERSION |
| BF840 | – | plastic surface mounted package; 3 leads | SOT23 |

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|-------------------------------|----------------------------------|------|------|------|
| V _{CBO} | collector-base voltage | open emitter | – | 40 | V |
| V _{CEO} | collector-emitter voltage | open base | – | 40 | V |
| V _{EBO} | emitter-base voltage | open collector | – | 4 | V |
| I _C | collector current (DC) | | – | 25 | mA |
| I _{CM} | peak collector current | | – | 25 | mA |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C; note 1 | – | 250 | mW |
| T _{stg} | storage temperature | | –65 | +150 | °C |
| T _j | junction temperature | | – | 150 | °C |
| T _{amb} | operating ambient temperature | | –65 | +150 | °C |

Note

1. Transistor mounted on an FR4 printed-circuit board.

NPN medium frequency transistor

BF840

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------|---|------------|-------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | note 1 | 500 | K/W |

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------|---------------------------|---|------|------|------|------|
| I_{CBO} | collector cut-off current | $I_E = 0; V_{CB} = 20\text{ V}$ | – | – | 100 | nA |
| I_{EBO} | emitter cut-off current | $I_C = 0; V_{EB} = 4\text{ V}$ | – | – | 100 | nA |
| h_{FE} | DC current gain | $I_C = 1\text{ mA}; V_{CE} = 10\text{ V}$ | 67 | – | 222 | |
| V_{BE} | base-emitter voltage | $I_C = 1\text{ mA}; V_{CE} = 10\text{ V}$ | 675 | 725 | 775 | mV |
| C_{re} | feedback capacitance | $I_C = 0; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$ | – | 0.3 | – | pF |
| f_T | transition frequency | $I_C = 1\text{ mA}; V_{CE} = 10\text{ V}; f = 100\text{ MHz}$ | – | 380 | – | MHz |

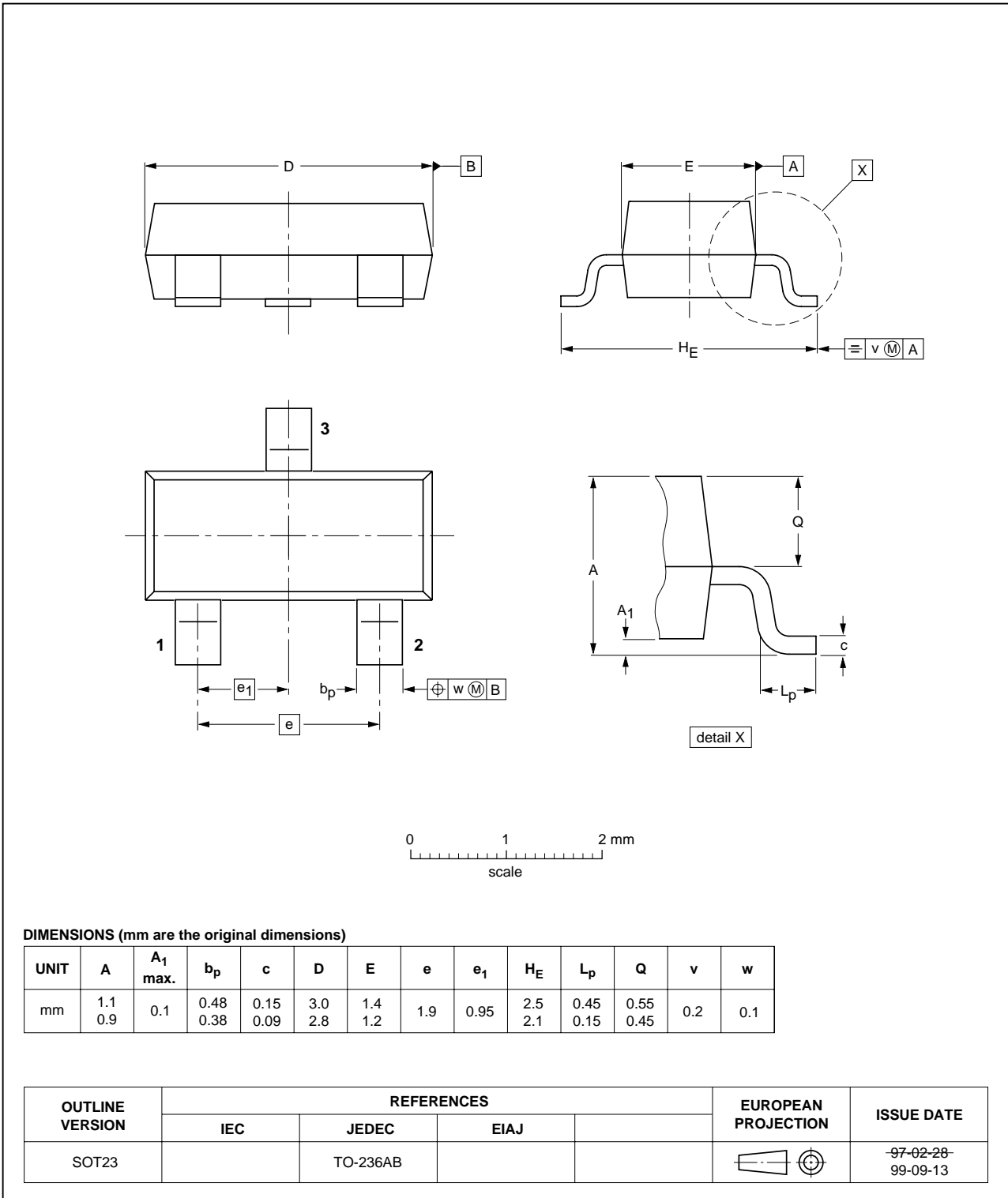
NPN medium frequency transistor

BF840

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



NPN medium frequency transistor

BF840

DATA SHEET STATUS

| LEVEL | DATA SHEET STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾⁽³⁾ | DEFINITION |
|-------|----------------------------------|----------------------------------|--|
| I | Objective data | Development | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice. |
| II | Preliminary data | Qualification | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product. |
| III | Product data | Production | This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). |

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2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.
3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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